



WLCSP10 3.40x1.96x0.10

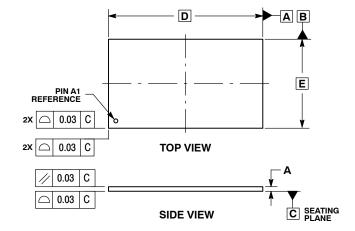
CASE 567PL ISSUE C

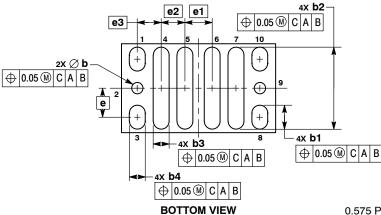
DATE 14 MAR 2018

NOTES:

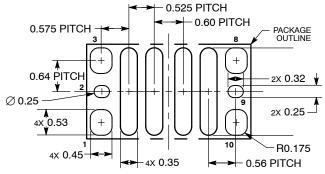
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M. 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.08	0.10	0.12	
b	0.22	0.25	0.28	
b1	0.50	0.53	0.56	
b2	1.78	1.81	1.84	
b3	0.32	0.35	0.38	
b4	0.32	0.35	0.38	
D	3.40 BSC			
E	1.96 BSC			
е	0.64 BSC			
e1	0.60 BSC			
e2	0.525 BSC			
е3	0.525 BSC			





RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



A = Assembly Location

Y = Year

W = Work Week

ZZ = Assembly Lot

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

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